



# SOT1672-1

plastic, low profile quad; flat leaded package; 112 terminals;  
0.65 mm pitch; 20 mm x 20 mm x 1.4 mm body

15 December 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	LQFP
<b>Package type industry code</b>	LQFP112
<b>Package style descriptive code</b>	LQFP (low profile quad flat package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026 BFA
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-6-2016
<b>Manufacturer package code</b>	98ASS23330W

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	20	-	mm
E	package width	-	-	20	-	mm
A	seated height	-	-	1.4	1.6	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	112	-	



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## 2. Package outline

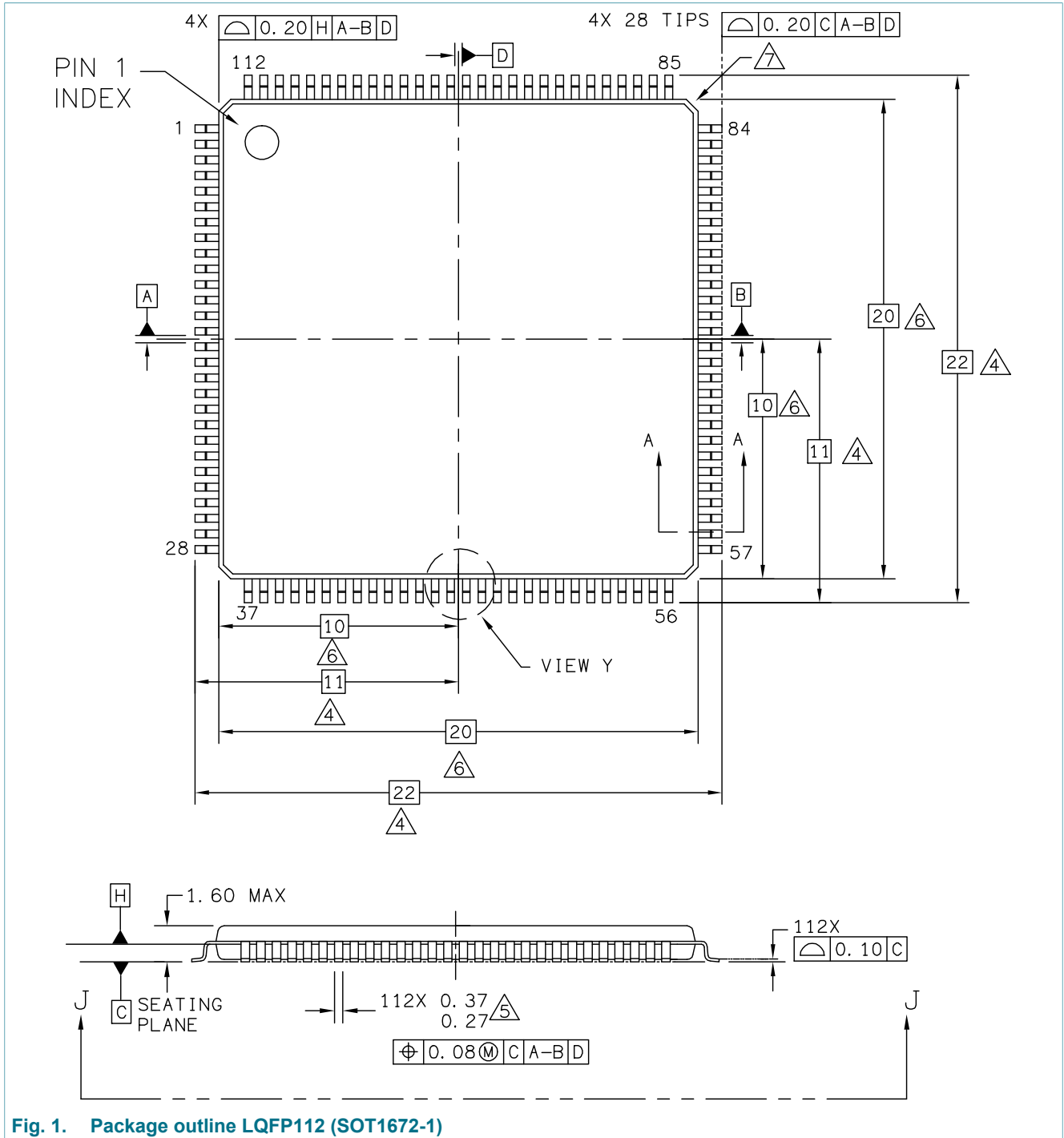


Fig. 1. Package outline LQFP112 (SOT1672-1)

plastic, low profile quad; flat leded package; 112 terminals; 0.65 mm pitch; 20 mm x 20 mm x 1.4 mm body

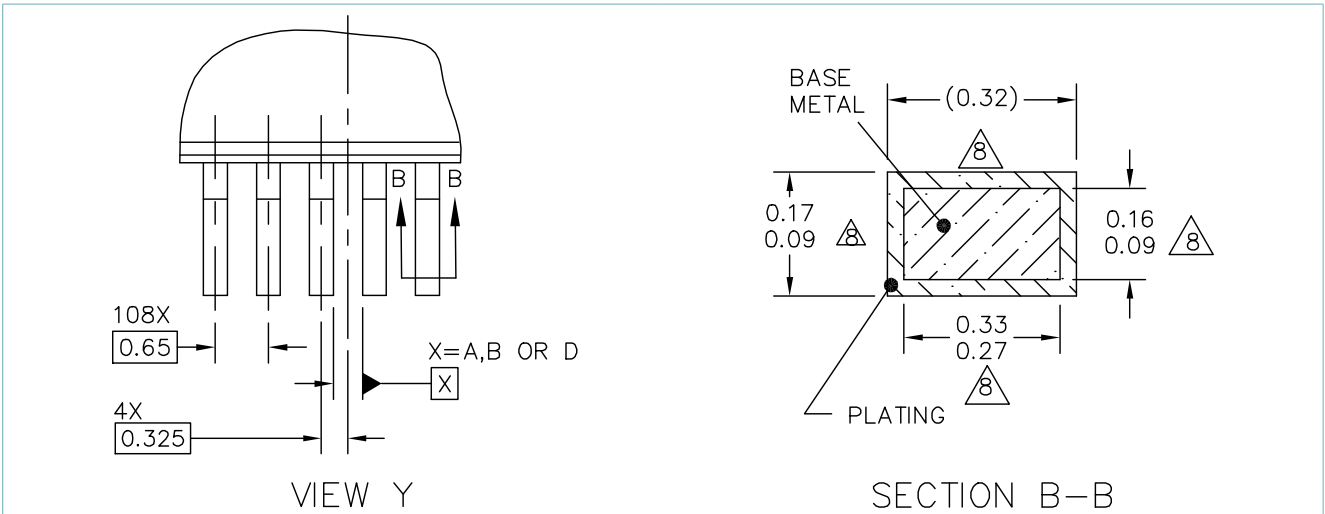


Fig. 2. Package outline dt1 LQFP112 (sot1672-1)

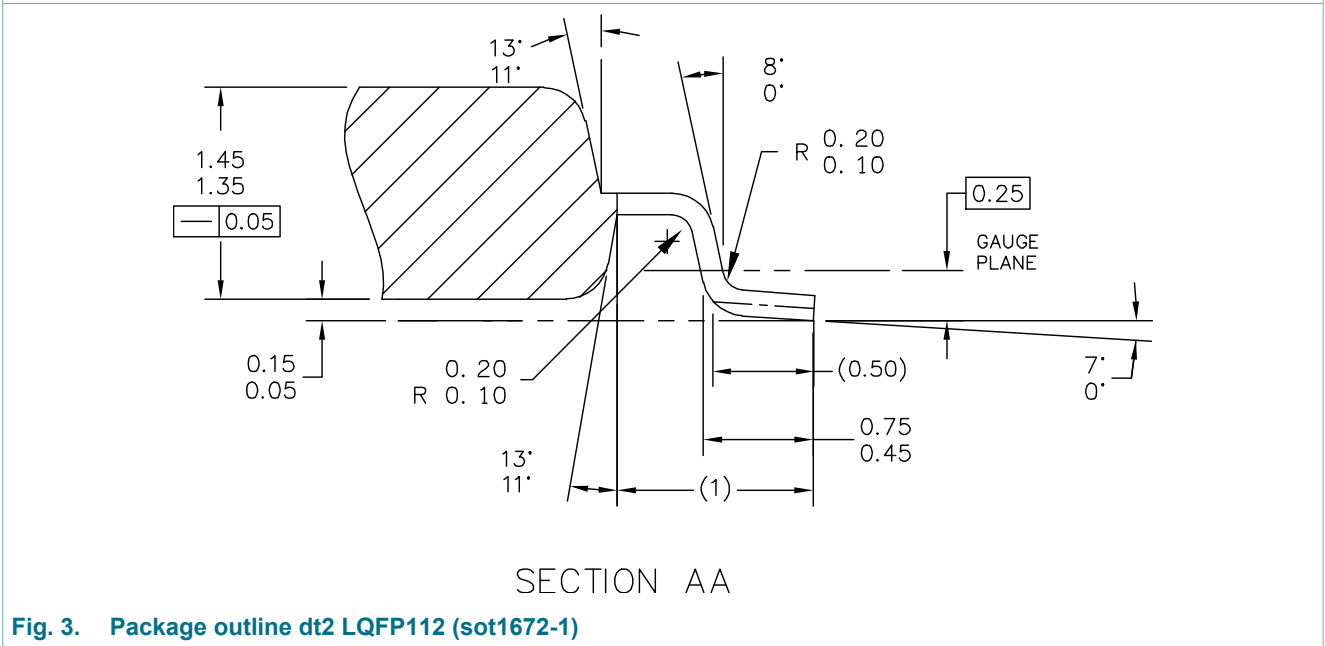


Fig. 3. Package outline dt2 LQFP112 (sot1672-1)

plastic, low profile quad; flat leaded package; 112 terminals; 0.65 mm pitch; 20 mm x 20 mm x 1.4 mm  
body

## NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.254 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.

**Fig. 4. Package outline note LQFP112 (sot1672-1)**

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### 3. Legal information

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